## IN THE CLAIMS

Page 12, line 1, change "Patent Claims" to --What is claimed is:--.

Claims 1-10 (cancelled).

11. (New) A method for generating a predetermined breaking line in a one-layer planar extending article having a working side and a decorative side, comprising a material with an inhomogeneous material density distribution, said method comprising the steps of:

directing a laser beam bundle to the working side for removing material in its beam path and thereby generating holes that are invisible from the decorative side;

the laser beam bundle and the planar extending article carrying out a relative movement with respect to one another so that the holes are generated in a row along the desired predetermined breaking line;

switching off the laser beam for a period of time determining the subsequent hole spacing when an amount of radiation generating a detector signal that is greater than a predetermined threshold signal impinges on a detector arranged on the decorative side;

gradually increasing the output of the laser beam from zero to its maximum nominal value before starting to produce each hole; and

switching off the laser beam immediately when a detector signal that is greater than the predetermined threshold is generated before reaching the maximum nominal value, which is caused by the absence of material or by a small amount of material of the planar extending article in the beam path (pseudo-hole) and prevents removal of the small amount of material and prevents overloading of the detector.

12. (New) The method for generating a predetermined breaking line in a multiple-layer planar extending article with a working side and a decorative side, in which the layer (final layer) forming the decorative side, said method comprising an inhomogeneous

material, comprising the steps of:

directing a laser beam bundle to the working side for removing material in its beam path and thereby generating holes that are invisible from the decorative side;

the laser beam bundle and the planar extending article carrying out a relative movement with respect to one another so that the holes are generated in a row along the desired predetermined breaking line;

switching off the laser beam for a period of time determining the subsequent hole spacing when an amount of radiation generating a detector signal that is greater than a predetermined threshold signal impinges upon a detector arranged on the decorative side;

reducing the output of the laser beam prior to penetration of the laser beam into the final layer at least until the amount of radiation still being emitted generates a signal smaller than the threshold with full detection;

activating the detector and subsequently increasing the laser beam again gradually to its maximum nominal value; and

switching off the laser beam immediately when a detector signal that is greater than the predetermined threshold is generated before reaching the maximum nominal value, which is caused by the absence of material or by a small amount of material of the planar extending article in the beam path (pseudo-hole) and prevents removal of the small amount of material and prevents overloading of the detector.

- 13. (New) The method according to claim 12, wherein a preparatory cut is introduced along the desired predetermined breaking line from the working side to, at most, the final layer before generating the row of holes, wherein the detector is desensitized or deactivated in order to protect it from possible overload.
  - 14. (New) The method according to claim 11, wherein the threshold signal is

selected in such a way that it is generated already by an amount of radiation that transmits through a residual wall of material of the planar extending article so that the holes are formed as blind holes.

- 15. (New) The method according to claim 12, wherein the threshold signal is selected in such a way that it is generated already by an amount of radiation that transmits through a residual wall of material of the planar extending article so that the holes are formed as blind holes.
- 16. (New) The method according to claim 11, wherein when working an inhomogeneous material that is a textile surface having an open structure on the decorative side, the threshold signal is selected in such a way that an amount of radiation that generates a signal greater than the threshold signal is not detected until after the direct penetration of the decorative side so that the holes are formed as microperforations.
- 17. (New) The method according to claim 12, wherein when working an inhomogeneous material that is a textile surface having an open structure on the decorative side, the threshold signal is selected in such a way that an amount of radiation that generates a signal greater than the threshold signal is not detected until after the direct penetration of the decorative side so that the holes are formed as microperforations.
- 18. (New) The method according to claim 14, wherein the laser beam impinges on the working side at an angle of less than 90° relative to the direction of the predetermined breaking line in order to increase the length of the beam path in the planar extending article, which leads to removal of a greater amount of material with hole spacing remaining constant or allows greater hole spacing.
- 19. (New) The method according to claim 15, wherein the laser beam impinges on the working side at an angle of less than 90° relative to the direction of the predetermined

breaking line in order to increase the length of the beam path in the planar extending article, which leads to removal of a greater amount of material with hole spacing remaining constant or allows greater hole spacing.

- 20. (New) The method according to claim 16, wherein the laser beam impinges on the working side at an angle of less than 90° relative to the direction of the predetermined breaking line in order to increase the length of the beam path in the planar extending article, which leads to removal of a greater amount of material with hole spacing remaining constant or allows greater hole spacing.
- 21. (New) The method according to claim 17, wherein the laser beam impinges on the working side at an angle of less than 90° relative to the direction of the predetermined breaking line in order to increase the length of the beam path in the planar extending article, which leads to removal of a greater amount of material with hole spacing remaining constant or allows greater hole spacing.
- 22. (New) The method according to claim 11, wherein the selected hole spacing between a pseudo-hole and a subsequent blind hole or microperforation is less than the other hole spacings.
- 23. (New) The method according to claim 12, wherein the selected hole spacing between a pseudo-hole and a subsequent blind hole or microperforation is less than the other hole spacings.
- 24. (New) The method according to claim 11, wherein the laser beam bundle is shaped in such a way on the working side that its cross section decreases toward the decorative side.

- 25. (New) The method according to claim 12, wherein the laser beam bundle is shaped in such a way on the working side that its cross section decreases toward the decorative side.
- 26. (New) The method according to claim 11, wherein when working an inhomogeneous material that is a woven material comprising longitudinal threads and cross threads, the selected hole spacing is less than the thread diameter.
- 27. (New) The method according to claim 12, wherein when working an inhomogeneous material that is a woven material comprising longitudinal threads and cross threads, the selected hole spacing is less than the thread diameter.
- 28. (New) The method according to claim 26, wherein the selected hole spacing is equal to half of the thread diameter so that each thread is weakened by two holes insofar as the hole is not generated over the thread diameter.
- 29. (New) The method according to claim 12, wherein the selected hole spacing is equal to half of the thread diameter so that each thread is weakened by two holes insofar as the hole is not generated over the thread diameter.